

Title (en)

PACKAGE FOR PROVIDING IMPROVED ELECTRICAL CONTACT AND METHODS FOR FORMING THE SAME

Title (de)

PACKUNG ZUR HERSTELLUNG EINES VERBESSERTEN ELEKTRISCHEN KONTAKTES UND DIESBEZÜGLICHE VERFAHREN

Title (fr)

BOITIER POUR FORMER UN MEILLEUR CONTACT ELECTRIQUE ET PROCEDES DE REALISATION CORRESPONDANTS

Publication

EP 1118120 A1 20010725 (EN)

Application

EP 99935373 A 19990629

Priority

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- US 16378198 A 19980930

Abstract (en)

[origin: WO0019532A1] A package for connecting electrical components to a substrate is disclosed. The package includes conductive castellations around the perimeter of the package. The castellations are configured to electrically connect to the substrate, and to electrically connect to conductive features at an interior portion of the package. In turn, electrical components may be electrically connected to the castellations. The package may be used to form a module by electrically connecting the electrical components to the package and integrating the components by connecting various components or portions thereof to other components or portions thereof.

IPC 1-7

H01L 23/498

IPC 8 full level

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CPC (source: EP)

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